



Material Content Data Sheet



Sales Product Name		TLE4254GS		Issued		28. August 2013		
MA#		MA000970056						
Package		PG-DSO-8-10		Weight*		81.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.802	2.20	2.20	21994	21994
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		113	
	non noble metal	zinc	7440-66-6	0.037	0.05		453	
	non noble metal	iron	7439-89-6	0.742	0.91		9052	
wire	non noble metal	copper	7440-50-8	30.114	36.76	37.73	367556	377174
	noble metal	gold	7440-57-5	0.160	0.20	0.20	1950	1950
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.12		1169
plating	plastics	epoxy resin	-	5.173	6.31		63138	
	inorganic material	silicondioxide	60676-86-0	42.629	52.02	58.45	520307	584614
	noble metal	gold	7440-57-5	0.002	0.00		25	
glue	noble metal	silver	7440-22-4	0.001	0.00		14	
	noble metal	palladium	7440-05-3	0.001	0.00		16	
	non noble metal	nickel	7440-02-0	0.038	0.05	0.05	462	517
*deviation	plastics	acrylic resin	-	0.248	0.30		3025	
	noble metal	silver	7440-22-4	0.879	1.07	1.37	10726	13751
Sum in total:						100.00		1000000

Important Remarks:

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